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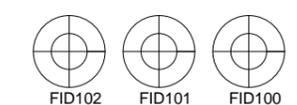
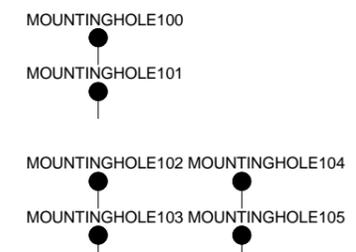
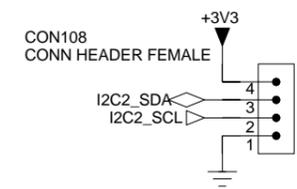
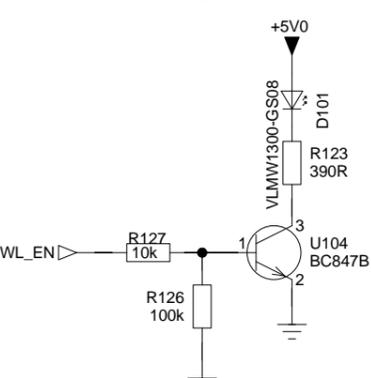
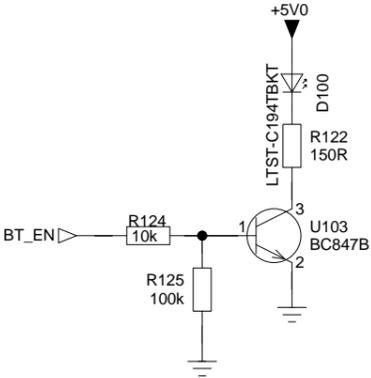
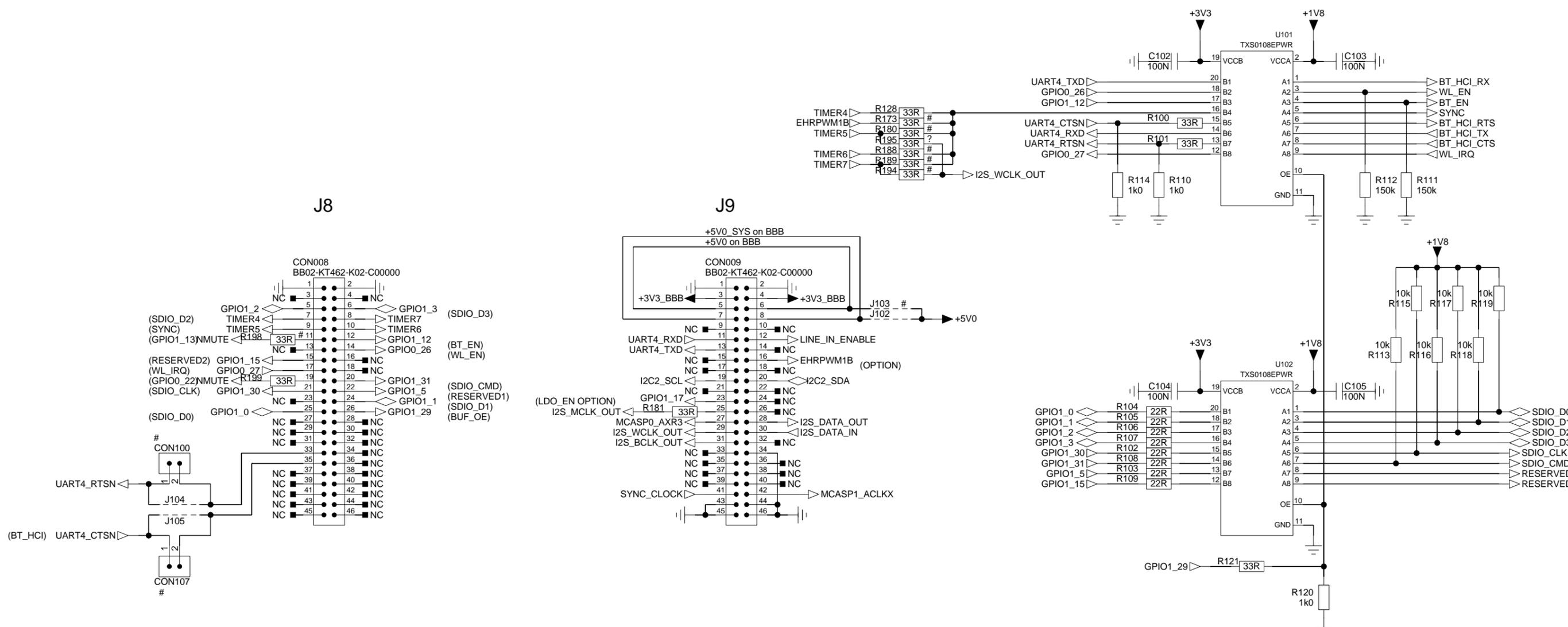
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René Gruber

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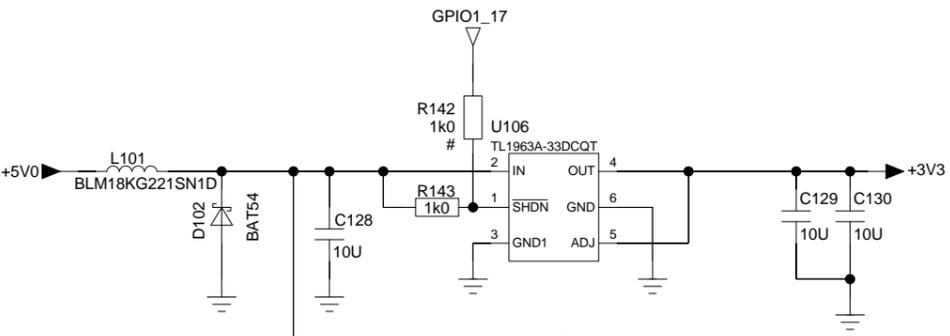
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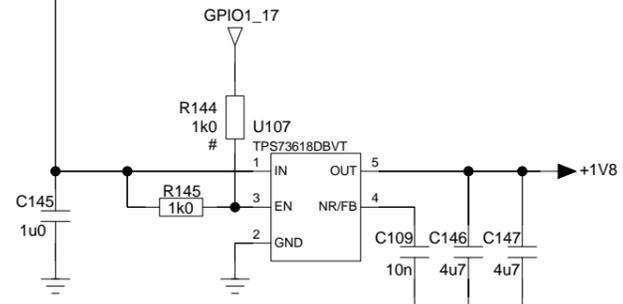
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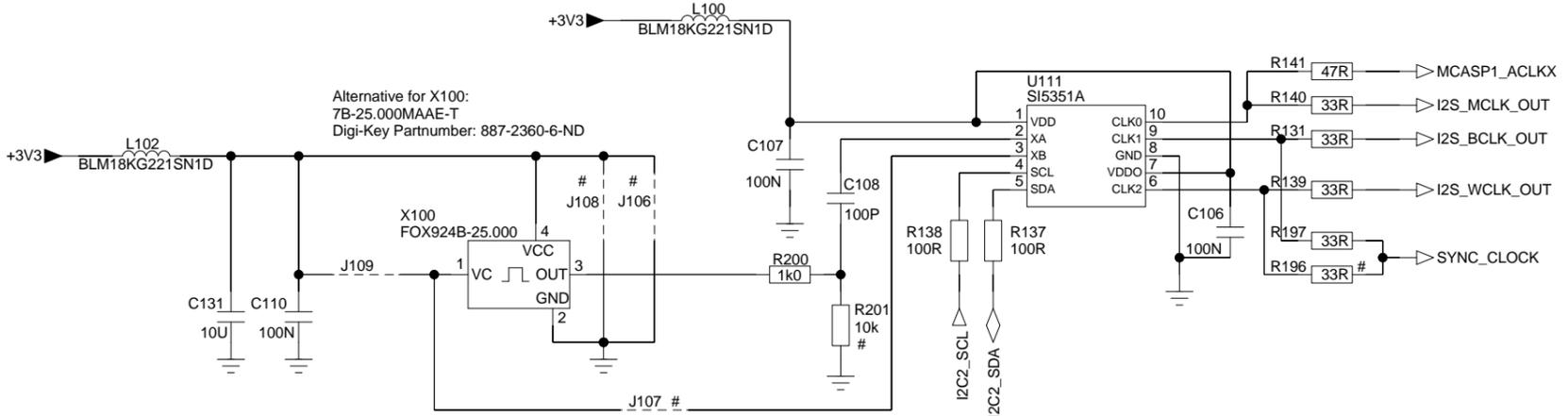
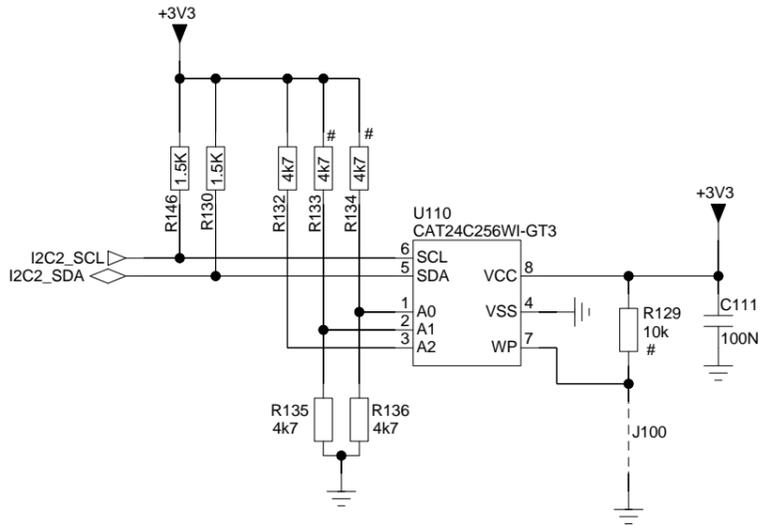
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(1.5A LDO)



(400mA LDO)



TITLE

# Power

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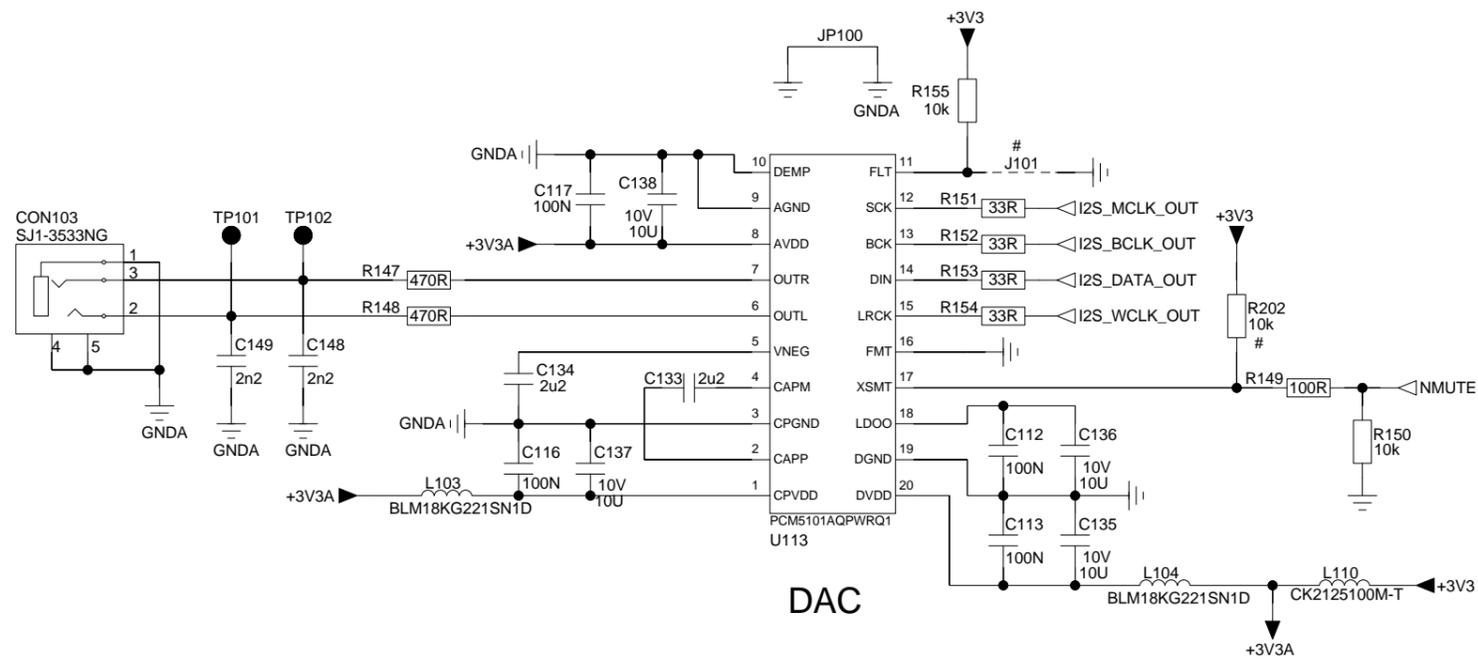
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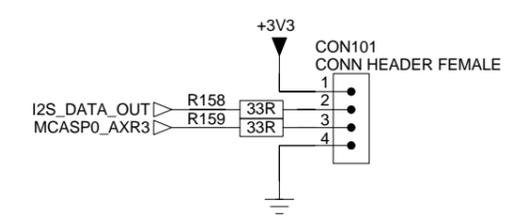
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AUX OUT

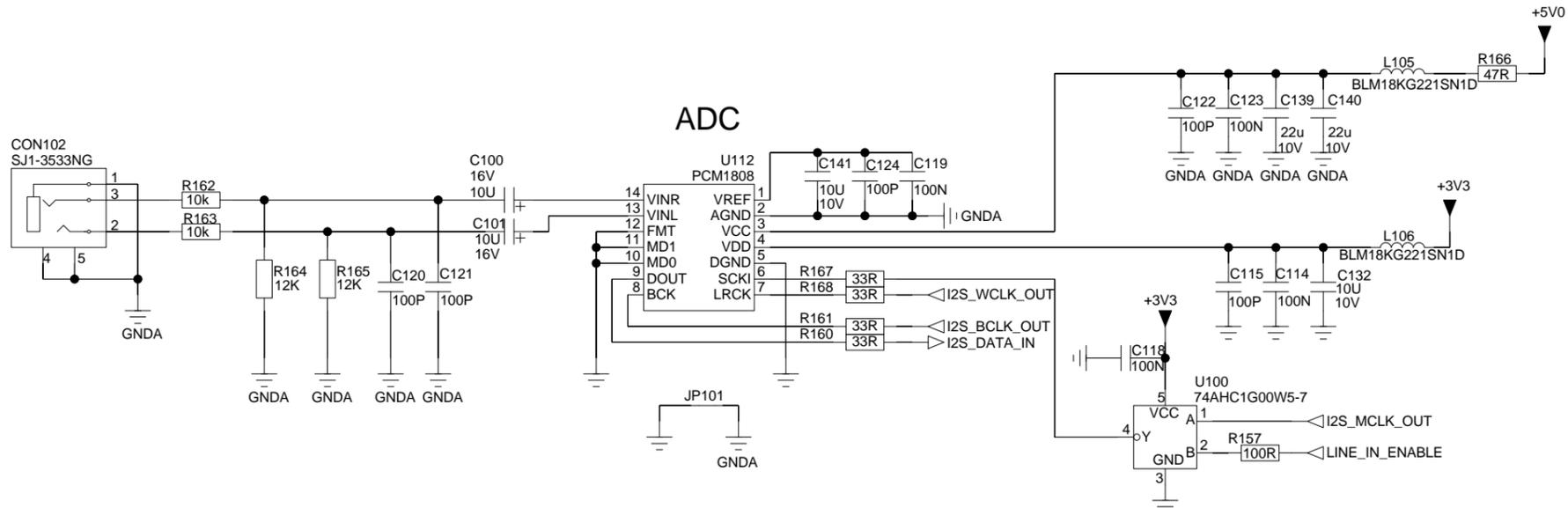


DAC

SPDIF/ DSD Header



AUX IN



ADC



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# Audio

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René Gruber		3 of 4
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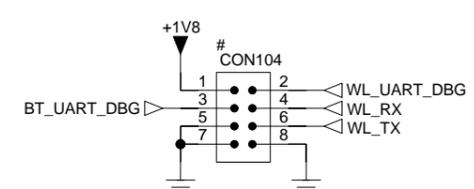
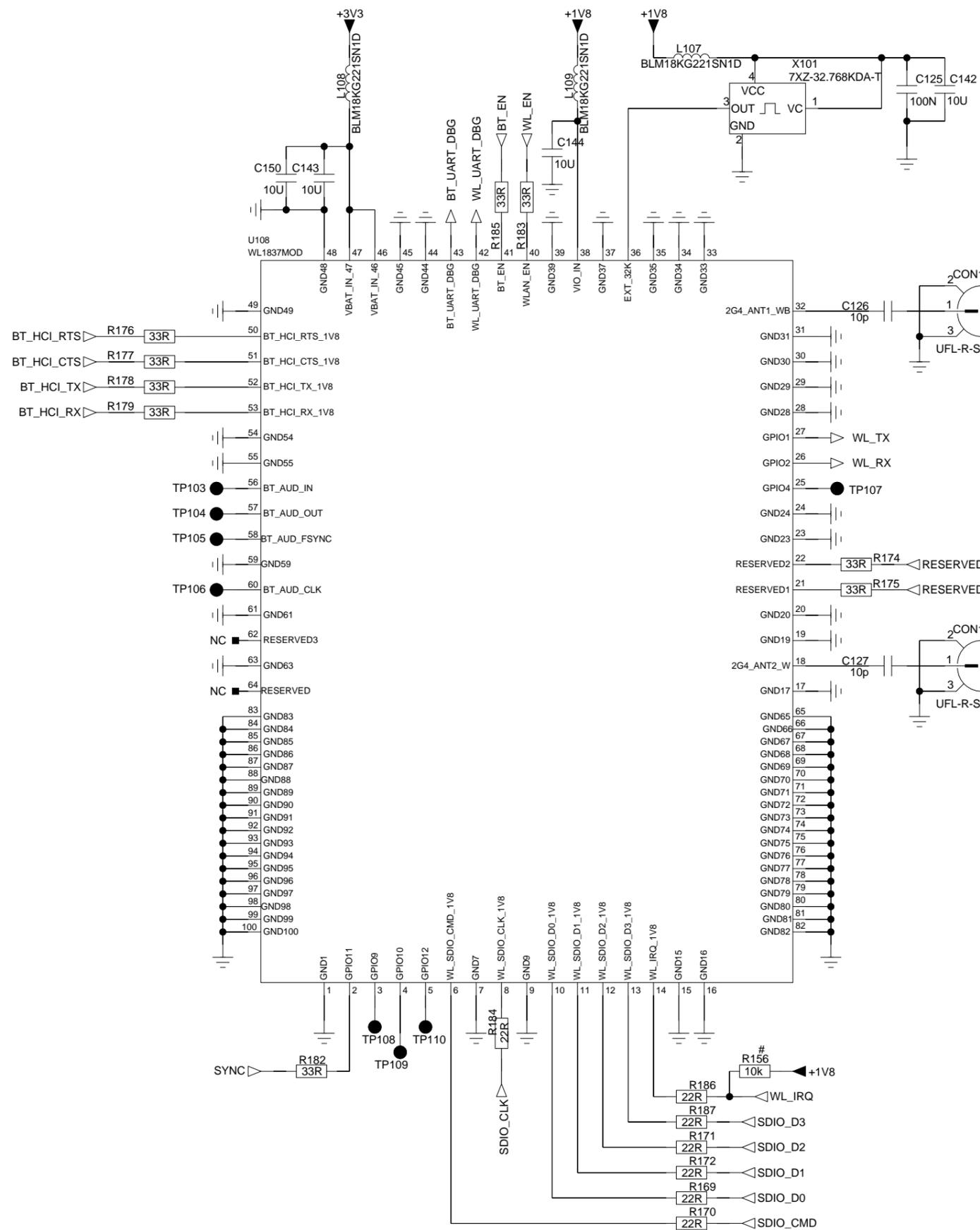
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TITLE

# Wifi

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